



DE3831787

Biblio

Desc

Claims

Drawing

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Adhesion bonding method

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EC Classification: [B29C65/34](#), [C09J5/06](#)

Equivalents: [ES2008030](#), [FR2620648](#), [JP1163283](#)

Abstract

Method of bonding two elements, in which the adhesion element used is an adhesive heated by a heating element which in turn is formed by a conductive resistance element incorporated into the adhesion element. The conductive element may be a metal wire, for example of copper, steel or constantan, and may have the form of a lattice or of essentially parallel wires or fibres. The conducting element is supplied with electrical current.

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1/6

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19. September 1988
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FIG 1

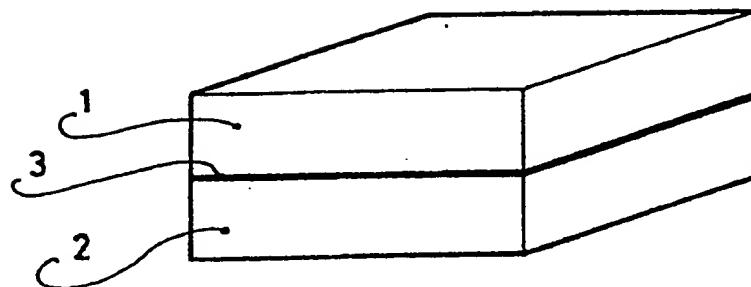


FIG 2

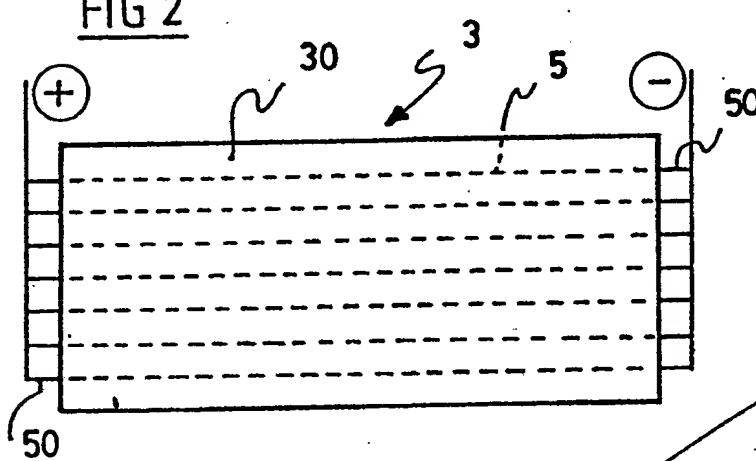


FIG 3



FIG 3a

FIG 3'a

